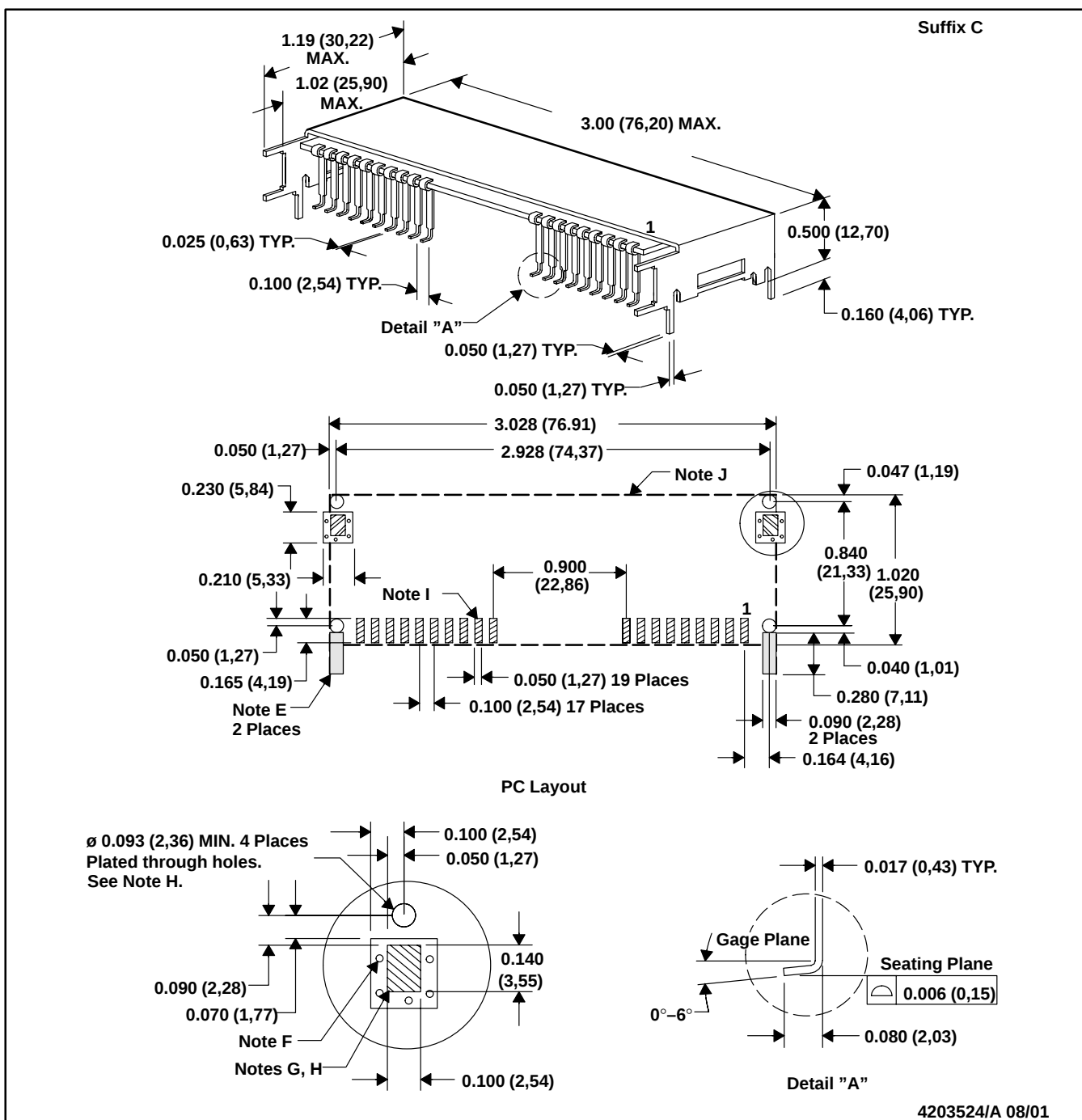


ENC (R-MSIP-G19)

METAL SINGLE-IN-LINE MODULE



- NOTES: A. All linear dimensions are in inches (mm).
 B. This drawing is subject to change without notice.
 C. 2 place decimals are ± 0.030 (± 0.76 mm).
 D. 3 place decimals are ± 0.010 (± 0.25 mm).
 E. Recommended mechanical keep out area.
 F. Vias are recommended to improve copper adhesion.
 G. Solder mask openings to copper island for solder joints to mechanical pins.

- H. The case is electrically uncommitted. The recommended connection is to the secondary ground plane.
 I. Power pin connections should utilize two or more vias per input, ground and output pin.
 J. Case outline reference

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